

## Claims

1. Casing (10) for transport of a toner mixture on its outer surface in a development device,
- 5
- whereby the wall of the casing (10) is essentially comprised of an electrically-conductive material and the outer surface of the casing (10) bears a layer made from nickel-copper.
- 10 2. Casing according to claim 1, in which the layer is generated via chemical deposition.
3. Casing according to claim 2, in which a chemical nickel-copper-phosphor deposition occurs as a chemical deposition process.
- 15 4. Casing according to any of the preceding claims, in which the layer comprises 1 to 2 % copper and 8 to 10 % phosphor.
5. Casing according to any of the preceding claims, in which the thickness of the layer lies in the range of 15 – 25  $\mu\text{m}$ .
- 20 6. Casing according to any of the preceding claims, in which the wall of the casing (10) is essentially comprised of aluminum.
- 25 7. Casing according to any of the preceding claims, in which the toner mixture is a two-component mixture which comprises ferromagnetic carrier particles and toner particles.
8. Method for production of a casing (10) according to any of the preceding claims,
- 30

in which a metal casing is chemically pre-treated,

and a chemical deposition subsequently occurs in which a nickel-copper-phosphor layer is generated.

5

9. Method according to claim 8, in which a layer is generated in the chemical deposition that comprises 1 to 2 % copper, 8 to 10 % phosphor and the remainder is essentially nickel.

- 10 10. Method according to any of the preceding claims, in which an aluminum casing on which a conductive layer is applied in a zincate etching after the chemical pre-treating is used as a casing,

a chemical pre-nickeling occurs thereupon,

15

and the chemical nickel-copper-phosphor deposition subsequently occurs.

11. Method according to any of the preceding claims, in which a chemical bath which comprises:

20

nickel sulfate 30 g/l, copper sulfate 0.6 to 1.5 g/l, sodium hyperphosphite 15 g/l, sodium citrate 50 g/l, ammonium chloride 40 g/l

is used for chemical nickel-copper-phosphor deposition.

25

12. Method according to claim 11, in which the bath has a pH value of 9.0 and a temperature of 75°C.